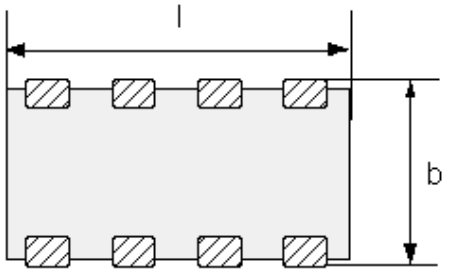
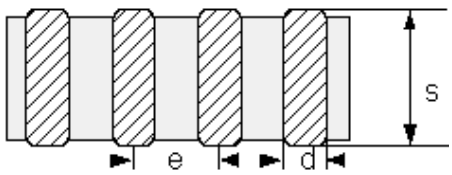
Preliminary data sheet
(parameters may be changed if necessary)

Designation System:

CA = **C**hip **A**rray
06 = Dimensions of the device **06**x12 (Length x width in 1/100 inch)
P = Design (**P**arallel internal structure)
4 = Number of elements
V = **V**aristor
150 = Typical varistor voltage
T = **T**hree layer termination (Ag/Ni/Sn)
HS = Designed for **H**igh **S**peed applications
G = Taped version (blister tape, 7" reel, 3000 pieces/reel)

Figure:





l = 3,2 ± 0,2
b = 1,6 ± 0,15
s = 0,9 max.
d = 0,4 ± 0,15
e = 0,76 ± 0,15

Coplanarity < 0.1

(All dimensions in mm)

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Electrical Data

Max. operating voltage	
RMS voltage	**V_{eff} = 14 V**
DC voltage	**V_{DC} = 16 V**
Varistor voltage (@ 1 mA, typ.)	**Vv = 150 V**
Max. varistor voltage (@ 1mA)	**Vv_{max} = 175 V**
Max. leakage current (@ 5 V; 25°C, unsoldered)	**Is_{max} = 3 µA**
Max. clamping voltage	**V_C = 350 V**
Capacitance (@ 1MHz, 1 V; 25°C, typ.)	**C = 3 pF**
Operating temperature	**-40 ... +85 °C**
Storage temperature (mounted parts)	**-40 ... +125 °C**
Termination material	**Ag/Ni/Sn**

Application Note

The described component is designed to meet ESD level 4 requirements acc. IEC61000-4-2 (8kV contact discharge 150pF, 330 Ω).

Due to the ultra low capacitance value in combination with low insertion losses up to 1 GHz this component is well suited for the ESD protection of high speed datalines (USB ports, Ethernet ports etc.) in e.g. note books, digital cameras, PDAs, printers....

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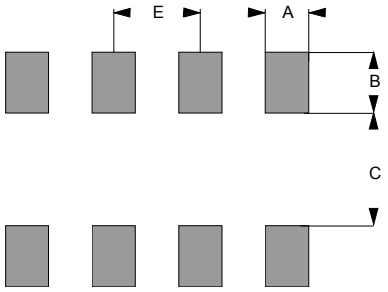
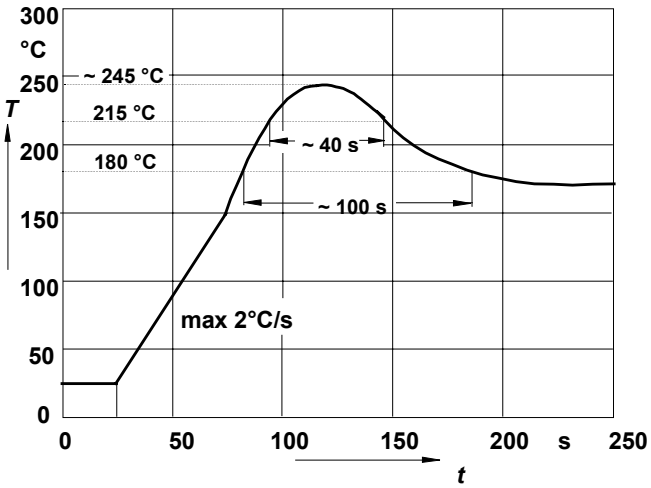
Recommended Geometry of Solder Pads

A = 0,5 mm
B = 0,7 mm
C = 1,2 mm
E = 0,76 mm



Recommended Soldering Temperature Profiles



The components should be soldered within 12 months after delivery from EPCOS. The parts are to be left in the original packing in order to avoid any soldering problems caused by oxidized terminals.
Storage temperature: -25 to 45°C.
Relative humidity: <75% annual average, <95% on max. 30 days in a year.

The usage of mild, non activated fluxes for soldering is recommended, as well as proper cleaning of the PCB.

Preliminary data sheet
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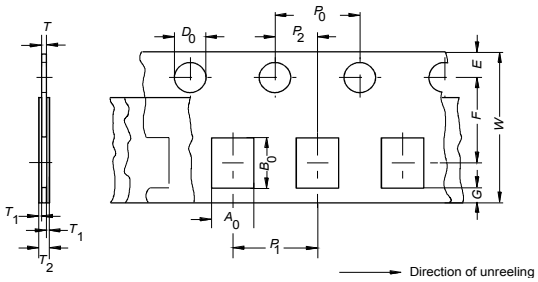
Taping According to IEC 60286-3

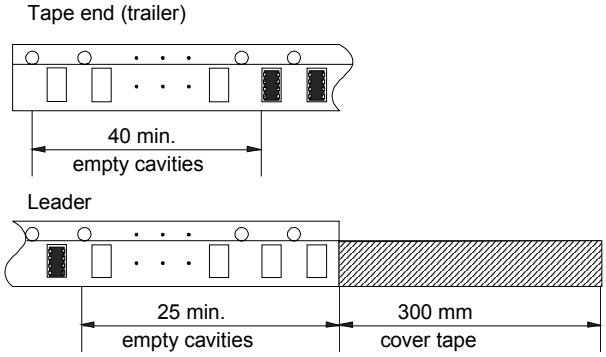
Dimensions and tolerances

Tape material: plastic embossed



Definition	Symbol	Dim.	Tolerance
Compartment width	A_0	1.9	± 0.2
Compartment length	B_0	3.5	± 0.2
Compartment height	K_0	1.3	max.
Sprocket hole diameter	D_0	1.5	+0.1 /-0
Compartment hole diameter	D_1	1.0	min.
Sprocket hole pitch	P_0	4.0	± 0.1 [1)]
Distance center hole to center compartment	P_2	2.0	± 0.05
Pitch of the component compartments	P_1	4.0	± 0.1
Tape width	W	8.0	± 0.3
Distance edge to center of hole	E	1.75	± 0.1
Distance center hole to center compartment	F	3.5	± 0.05
Overall thickness	T_2	2.5	max.

[1)] ≤ ± 0.2 mm over any 10 pitches



Preliminary data sheet
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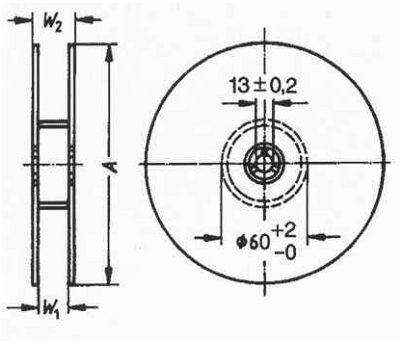
Package

Dimensions approx. 220 x 200 mm.

6 bags in cardboard box; dimensions approx. 250 x 220 x 130 mm.

Package: 8 mm tape

Reel material: plastic



Definition	Symbol	Dim.	Tol.
Reel diameter	A	180	-2
Reel width (inside)	W_1	8.4	+1.5 /-0
Reel width (outside)	W_2	14.4	max.